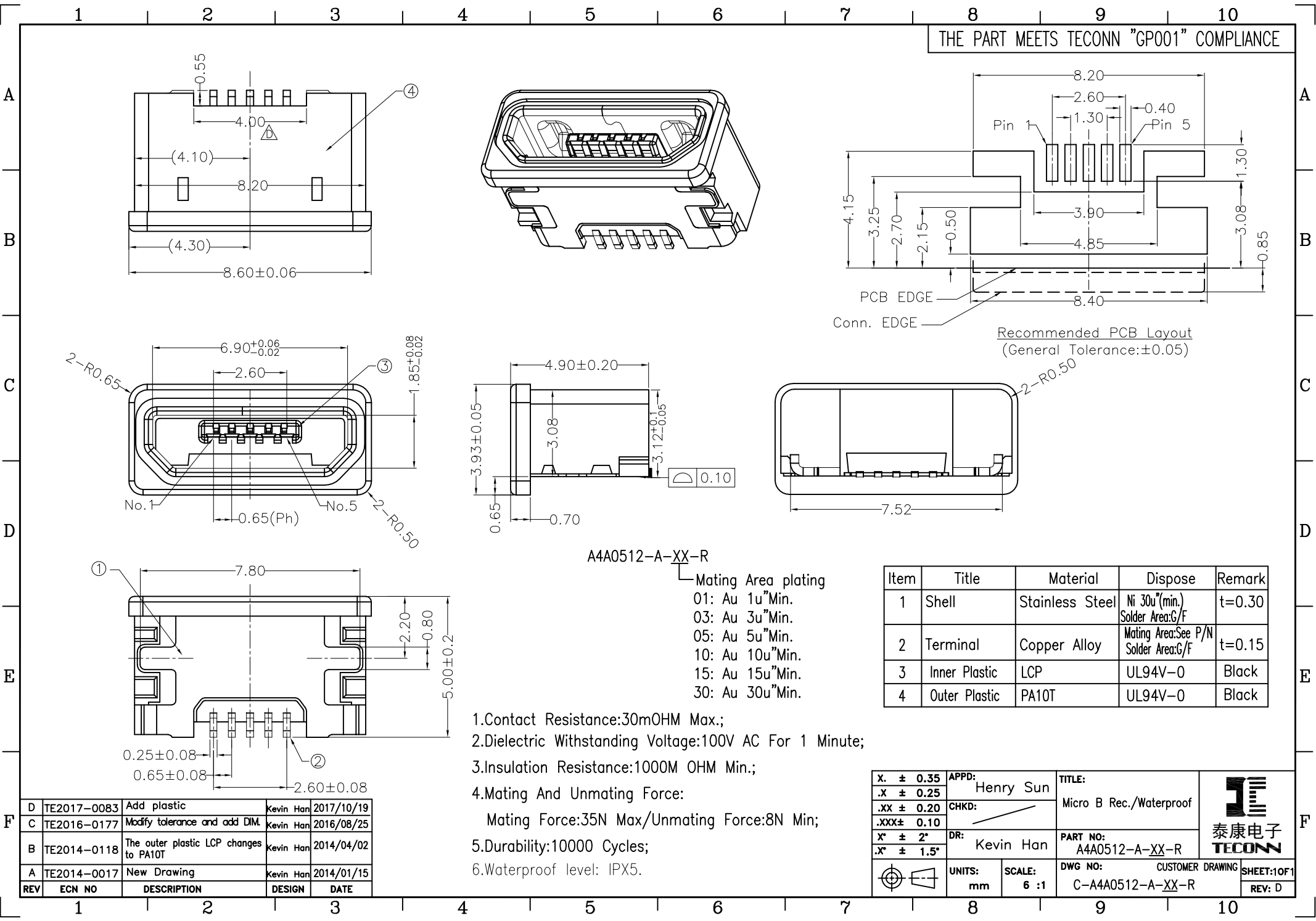


THE PART MEETS TECONN "GP001" COMPLIANCE




A4A0512-A-XX-R

- Mating Area plating
- 01: Au 1u"Min.
- 03: Au 3u"Min.
- 05: Au 5u"Min.
- 10: Au 10u"Min.
- 15: Au 15u"Min.
- 30: Au 30u"Min.

Item	Title	Material	Dispose	Remark
1	Shell	Stainless Steel	Ni 30u"(min.) Solder Area:G/F	t=0.30
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Area:G/F	t=0.15
3	Inner Plastic	LCP	UL94V-0	Black
4	Outer Plastic	PA10T	UL94V-0	Black

- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;
- 6.Waterproof level: IPX5.

REV	ECN NO	DESCRIPTION	DESIGN	DATE
D	TE2017-0083	Add plastic	Kevin Han	2017/10/19
C	TE2016-0177	Modify tolerance and add DIM.	Kevin Han	2016/08/25
B	TE2014-0118	The outer plastic LCP changes to PA10T	Kevin Han	2014/04/02
A	TE2014-0017	New Drawing	Kevin Han	2014/01/15

X: ± 0.35	APPD: Henry Sun	TITLE: Micro B Rec./Waterproof	 泰康电子 TECONN
.X ± 0.25	CHKD: /	PART NO: A4A0512-A-XX-R	
.XX ± 0.20	DR: Kevin Han	DWG NO: C-A4A0512-A-XX-R	
.XXX ± 0.10		CUSTOMER DRAWING	
X' ± 2°	UNITS: mm	SCALE: 6 : 1	SHEET: 10F1
.X' ± 1.5°			REV: D